

## General Description

The GreenMOS<sup>®</sup> high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS<sup>®</sup> Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

## Features

- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Ultra-fast and robust body diode




## Applications

- PC power
- Telecom power
- Server power
- EV Charger
- Motor driver

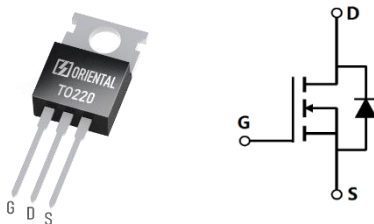
## Key Performance Parameters

| Parameter                      | Value | Unit       |
|--------------------------------|-------|------------|
| $V_{DS, min} @ T_{j(max)}$     | 700   | V          |
| $I_D, pulse$                   | 75    | A          |
| $R_{DS(ON), max} @ V_{GS}=10V$ | 140   | m $\Omega$ |
| $Q_g$                          | 55.2  | nC         |

## Marking Information

| Product Name  | Package | Marking      |
|---------------|---------|--------------|
| OSG65R140PSZF | TO220   | OSG65R140PSZ |

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

| Parameter   | Symbol         | Value      | Unit             |
|---|----------------|------------|------------------|
| Drain-source voltage  | $V_{DS}$       | 650        | V                |
| Gate-source voltage   | $V_{GS}$       | $\pm 30$   | V                |
| Continuous drain current <sup>1)</sup> , $T_C=25^\circ\text{C}$         | $I_D$          | 25         | A                |
| Continuous drain current <sup>1)</sup> , $T_C=100^\circ\text{C}$        |                | 16         |                  |
| Pulsed drain current <sup>2)</sup> , $T_C=25^\circ\text{C}$             | $I_{D, pulse}$ | 75         | A                |
| Continuous diode forward current <sup>1)</sup> , $T_C=25^\circ\text{C}$ | $I_S$          | 25         | A                |
| Diode pulsed current <sup>2)</sup> , $T_C=25^\circ\text{C}$             | $I_{S, pulse}$ | 75         | A                |
| Power dissipation <sup>3)</sup> , $T_C=25^\circ\text{C}$                | $P_D$          | 219        | W                |
| Single pulsed avalanche energy <sup>5)</sup>                            | $E_{AS}$       | 1000       | mJ               |
| MOSFET dv/dt ruggedness, $V_{DS}=0\dots 480\text{ V}$                   | dv/dt          | 50         | V/ns             |
| Reverse diode dv/dt, $V_{DS}=0\dots 480\text{ V}$ , $I_{SD}\leq I_D$    | dv/dt          | 50         | V/ns             |
| Operation and storage temperature                                       | $T_{stg}, T_j$ | -55 to 150 | $^\circ\text{C}$ |

**Thermal Characteristics**

| Parameter  | Symbol          | Value | Unit               |
|--|-----------------|-------|--------------------|
| Thermal resistance, junction-case                  | $R_{\theta JC}$ | 0.57  | $^\circ\text{C/W}$ |
| Thermal resistance, junction-ambient <sup>4)</sup> | $R_{\theta JA}$ | 62    | $^\circ\text{C/W}$ |

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

| Parameter                        | Symbol       | Min. | Typ. | Max. | Unit          | Test condition  |
|----------------------------------|--------------|------|------|------|---------------|---|
| Drain-source breakdown voltage   | $BV_{DSS}$   | 650  |      |      | V             | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$                                 |
|                                  |              | 700  | 750  |      |               | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$ ,<br>$T_j=150^\circ\text{C}$    |
| Gate threshold voltage           | $V_{GS(th)}$ | 3.0  |      | 4.5  | V             | $V_{DS}=V_{GS}$ , $I_D=1\text{ mA}$                                     |
| Drain-source on-state resistance | $R_{DS(on)}$ |      | 0.12 | 0.14 | $\Omega$      | $V_{GS}=10\text{ V}$ , $I_D=12.5\text{ A}$                              |
|                                  |              |      | 0.30 |      |               | $V_{GS}=10\text{ V}$ , $I_D=12.5\text{ A}$ ,<br>$T_j=150^\circ\text{C}$ |
| Gate-source leakage current      | $I_{GSS}$    |      |      | 100  | nA            | $V_{GS}=30\text{ V}$  |
|                                  |              |      |      | -100 |               | $V_{GS}=-30\text{ V}$   |
| Drain-source leakage current     | $I_{DSS}$    |      |      | 10   | $\mu\text{A}$ | $V_{DS}=650\text{ V}$ , $V_{GS}=0\text{ V}$                             |
| Gate resistance                  | $R_G$        |      | 16.7 |      | $\Omega$      | $f=1\text{ MHz}$ , Open drain   |

### Dynamic Characteristics

| Parameter                    | Symbol       | Min. | Typ.   | Max. | Unit | Test condition  |
|------------------------------|--------------|------|--------|------|------|---|
| Input capacitance            | $C_{iss}$    |      | 2855.4 |      | pF   | $V_{GS}=0\text{ V}$ ,<br>$V_{DS}=50\text{ V}$ ,<br>$f=100\text{ kHz}$                       |
| Output capacitance           | $C_{oss}$    |      | 151.1  |      | pF   |   |
| Reverse transfer capacitance | $C_{rss}$    |      | 7.7    |      | pF   |   |
| Turn-on delay time           | $t_{d(on)}$  |      | 56.3   |      | ns   | $V_{GS}=10\text{ V}$ ,<br>$V_{DS}=400\text{ V}$ ,<br>$R_G=2\ \Omega$ ,<br>$I_D=16\text{ A}$ |
| Rise time                    | $t_r$        |      | 68.8   |      | ns   |   |
| Turn-off delay time          | $t_{d(off)}$ |      | 108.5  |      | ns   |   |
| Fall time                    | $t_f$        |      | 31.6   |      | ns   |   |

### Gate Charge Characteristics

| Parameter            | Symbol        | Min. | Typ. | Max. | Unit | Test condition   |
|----------------------|---------------|------|------|------|------|--|
| Total gate charge    | $Q_g$         |      | 55.2 |      | nC   | $V_{GS}=10\text{ V}$ ,<br>$V_{DS}=400\text{ V}$ ,<br>$I_D=16\text{ A}$ |
| Gate-source charge   | $Q_{gs}$      |      | 13.7 |      | nC   |  |
| Gate-drain charge    | $Q_{gd}$      |      | 24.0 |      | nC   |  |
| Gate plateau voltage | $V_{plateau}$ |      | 6.8  |      | V    |  |

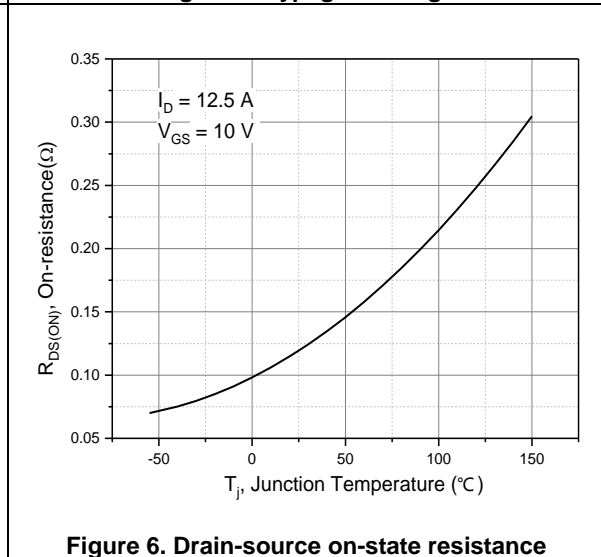
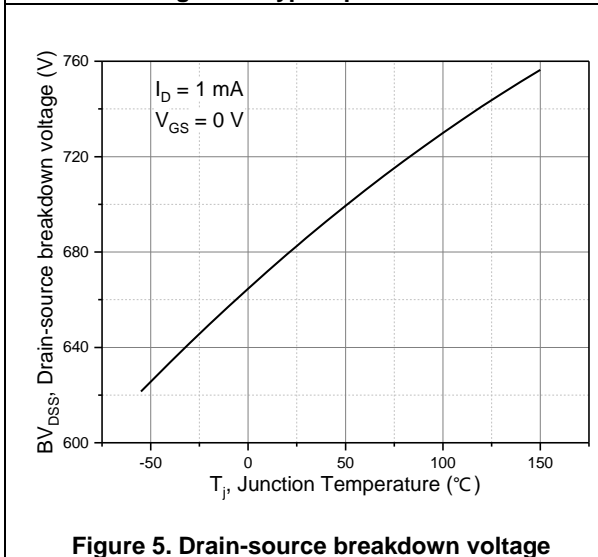
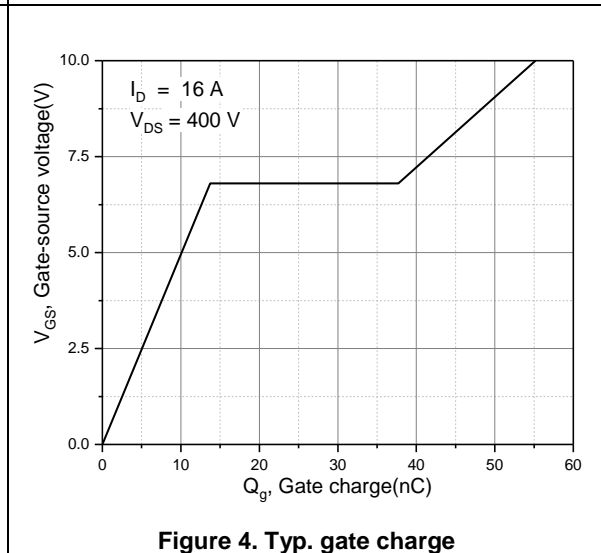
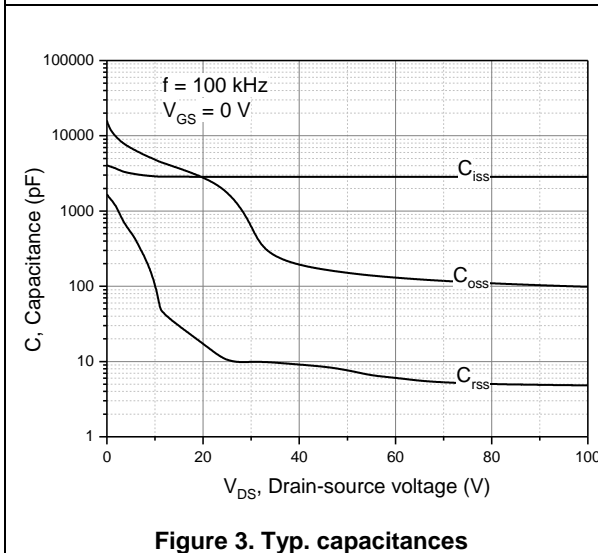
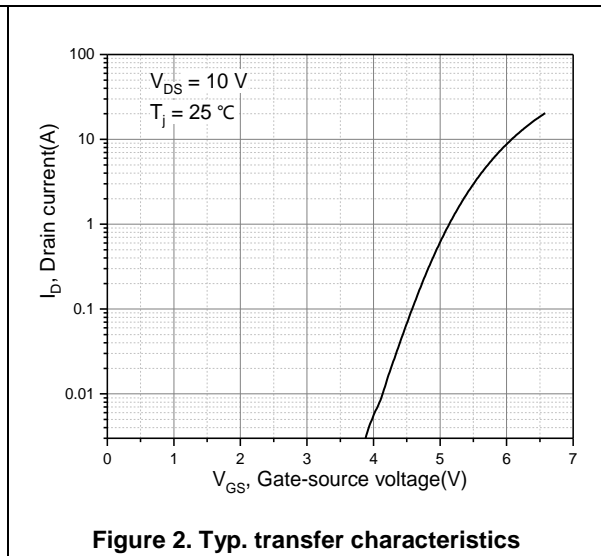
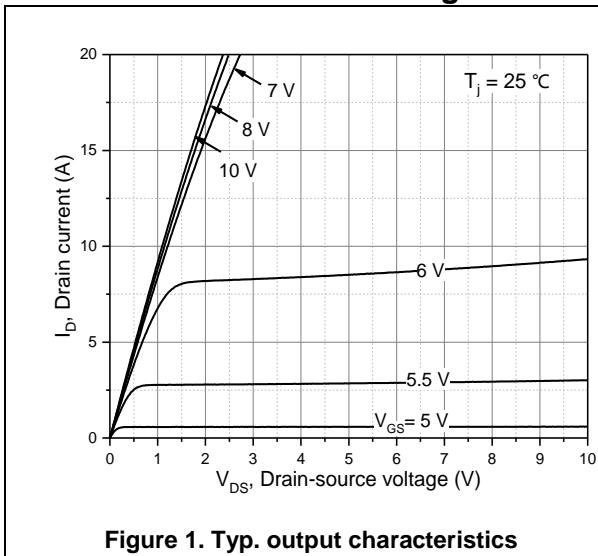
### Body Diode Characteristics

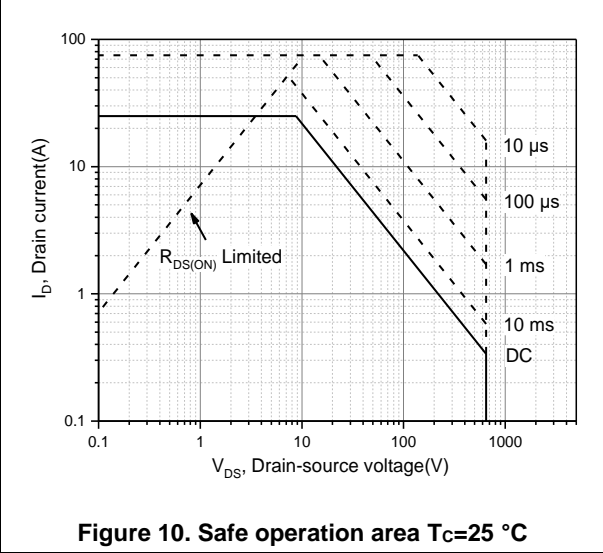
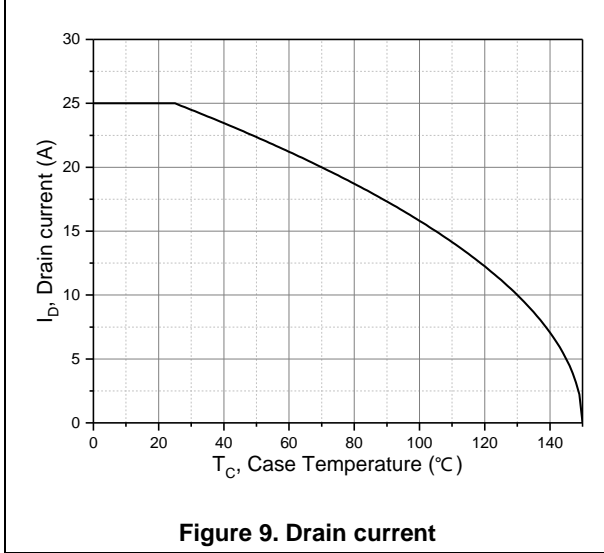
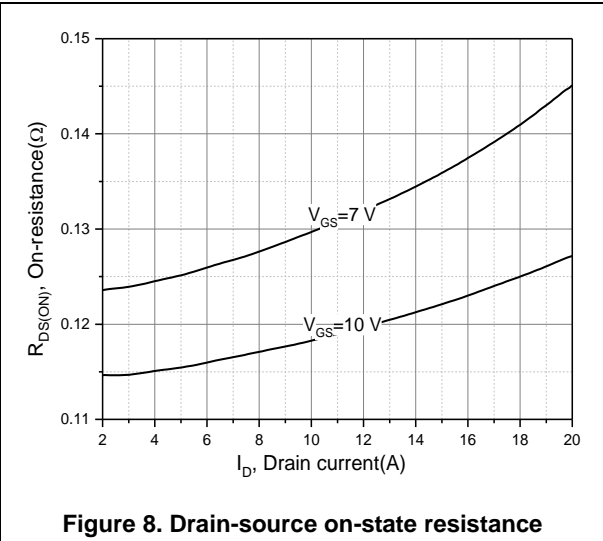
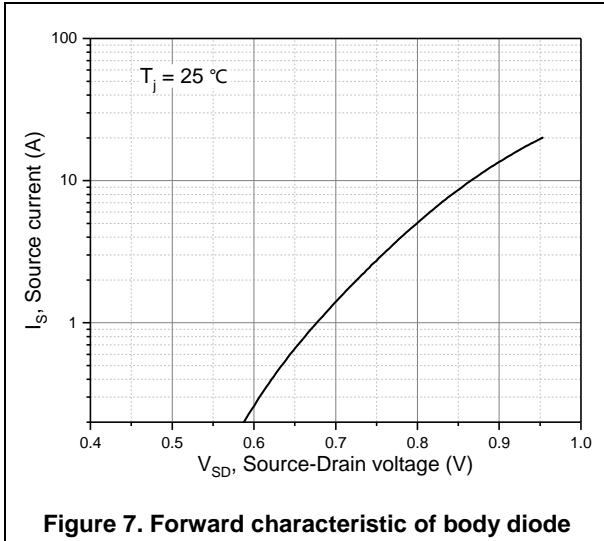
| Parameter                     | Symbol    | Min. | Typ.  | Max. | Unit          | Test condition  |
|-------------------------------|-----------|------|-------|------|---------------|---|
| Diode forward voltage         | $V_{SD}$  |      |       | 1.3  | V             | $I_S=25\text{ A}$ ,<br>$V_{GS}=0\text{ V}$              |
| Reverse recovery time         | $t_{rr}$  |      | 126.0 |      | ns            | $I_S=16\text{ A}$ ,<br>$di/dt=100\text{ A}/\mu\text{s}$ |
| Reverse recovery charge       | $Q_{rr}$  |      | 0.7   |      | $\mu\text{C}$ |   |
| Peak reverse recovery current | $I_{rrm}$ |      | 10.6  |      | A             |   |

### Note

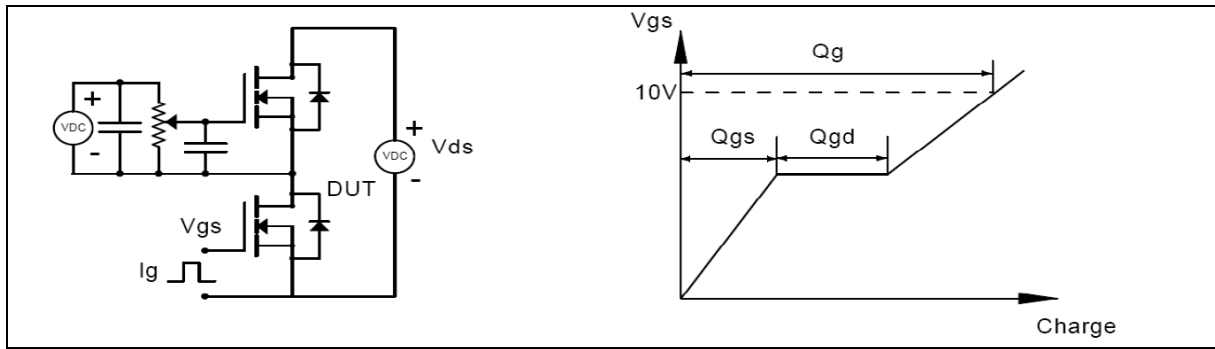
- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .
- 5)  $V_{DD}=100\text{ V}$ ,  $V_{GS}=10\text{ V}$ ,  $L=60\text{ mH}$ , starting  $T_j=25\text{ }^\circ\text{C}$ .

**Electrical Characteristics Diagrams**

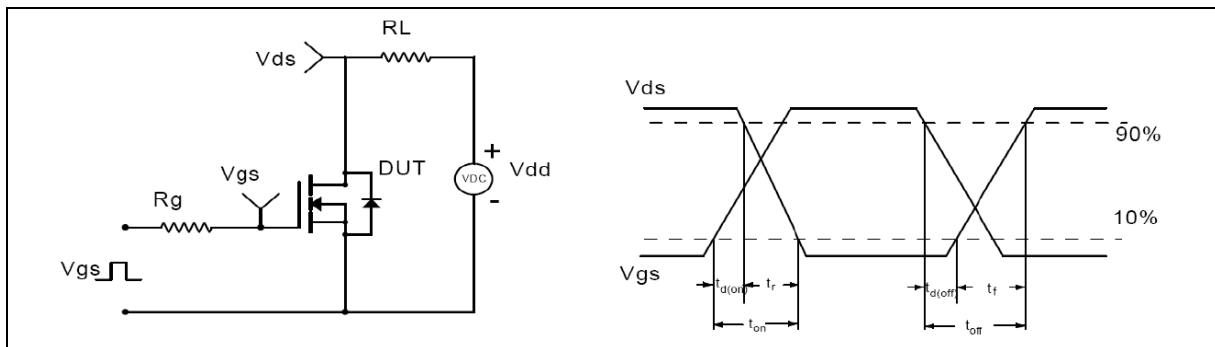




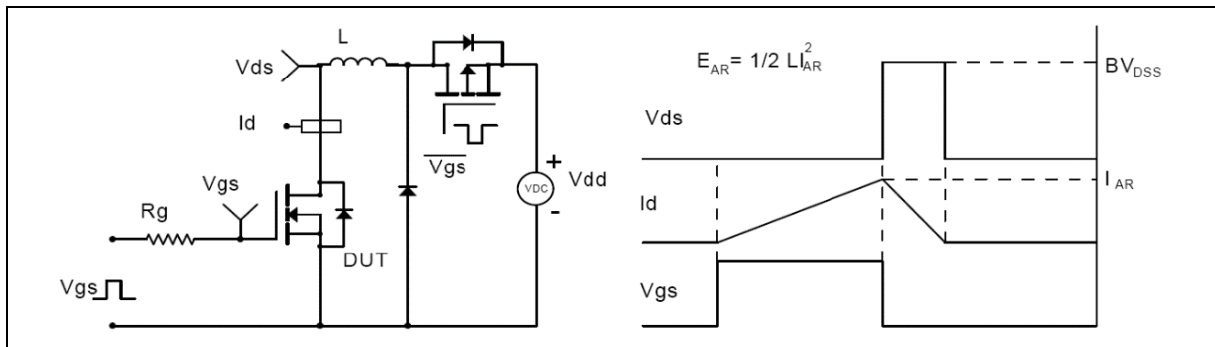
**Test circuits and waveforms**



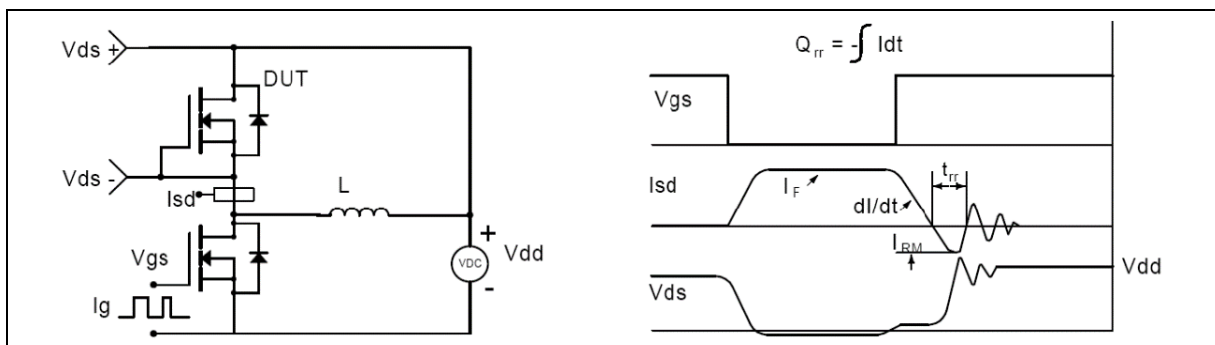
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

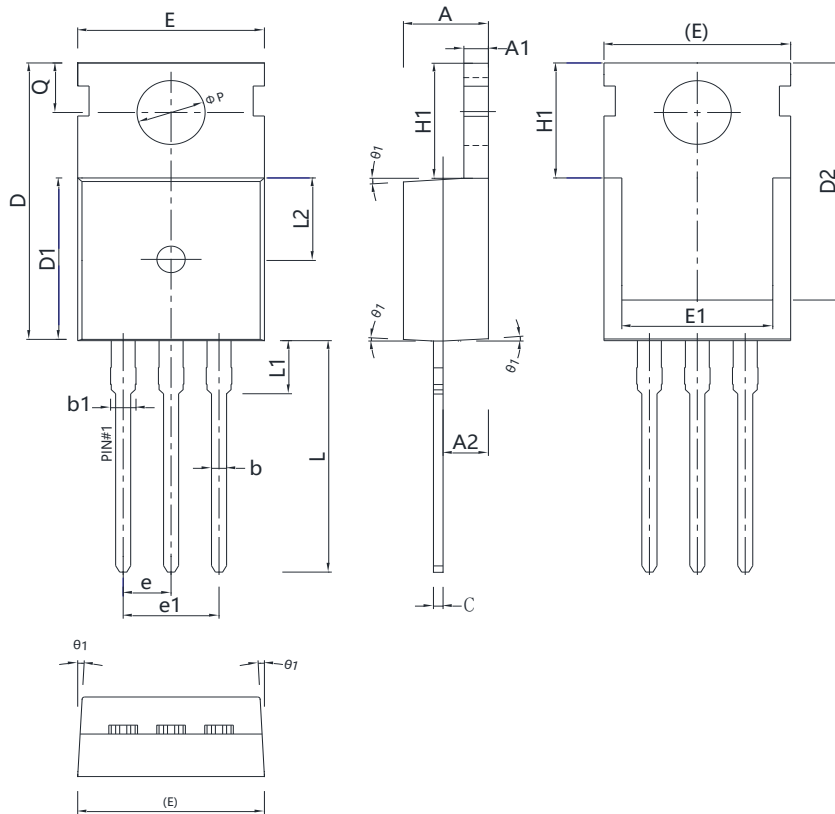


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

**Package Information**



| Symbol | mm       |       |       |
|--------|----------|-------|-------|
|        | Min      | Nom   | Max   |
| A      | 4.40     | 4.50  | 4.60  |
| A1     | 1.27     | 1.30  | 1.33  |
| A2     | 2.30     | 2.40  | 2.50  |
| b      | 0.70     | -     | 0.90  |
| b1     | 1.27     | -     | 1.40  |
| c      | 0.45     | 0.50  | 0.60  |
| D      | 15.30    | 15.70 | 16.10 |
| D1     | 9.10     | 9.20  | 9.30  |
| D2     | 13.10    | -     | 13.70 |
| E      | 9.70     | 9.90  | 10.20 |
| E1     | 7.80     | 8.00  | 8.20  |
| e      | 2.54 BSC |       |       |
| e1     | 5.08 BSC |       |       |
| H1     | 6.30     | 6.50  | 6.70  |
| L      | 12.78    | 13.08 | 13.38 |
| L1     | -        | -     | 3.50  |
| L2     | 4.60 REF |       |       |
| ΦP     | 3.55     | 3.60  | 3.65  |
| Q      | 2.73     | -     | 2.87  |
| θ1     | 1°       | 3°    | 5°    |

Version1: TO220-J package outline dimension

### Ordering Information

| Package Type | Units/ Tube | Tubes/ Inner Box | Units/ Inner Box | Inner Boxes/ Carton Box | Units/ Carton Box |
|--------------|-------------|------------------|------------------|-------------------------|-------------------|
| TO220-J      | 50          | 20               | 1000             | 5                       | 5000              |

### Product Information

| Product       | Package | Pb Free | RoHS | Halogen Free |
|---------------|---------|---------|------|--------------|
| OSG65R140PSZF | TO220   | yes     | yes  | yes          |

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